## Photobolometer based on high mobility graphene hetero-stacks as enabling technology for sub-THz wireless links

## A. Boschi<sup>1</sup>

A. Montanaro<sup>2</sup>, G. Ducournau<sup>3</sup>, V. Miseikis<sup>1</sup>, M. Romagnoli<sup>2</sup>, V. Sorianello<sup>2</sup>, S. Pezzini<sup>4</sup>, C. Coletti<sup>1</sup> <sup>1</sup> Istituto Italiano di Tecnologia, CNI@NEST - 56127 Pisa, Italy

<sup>2</sup> CNIT, Photonic Networks and Technologies Lab - 56124 Pisa, Italy

<sup>3</sup> Université de Lille, CNRS, Centrale Lille, Univ. Polytechnique Hauts-de-France, UMR CNRS 8520 IEMN,

Institut d'Electronique de Microélectronique et de Nanotechnologie - 59000 Lille, France

<sup>4</sup> NEST, Istituto Nanoscienze-CNR and Scuola Normale Superiore – 56127 Pisa, Italy

alex.boschi@iit.it

Transmitting and detecting multi Gbit/s wireless signals at short-distances (~ few m), with low latency (< 0.1 ms) and over sub-THz carrier frequencies is one of the main challenge for 6G communication systems[1], but it can also enable radar applications in food inspection, medical imaging and non-destructive quality control [2,3]. Current electronic and optoelectronic technologies working in sub-THz window suffer of different drawbacks, such as large phase noise, carrier frequency instabilities, limited frequency tunability and large components footprint [4].

In this research project, we are implementing a new approach based on graphene integrated photonics to overcome aforementioned technical bottlenecks.

We assembled high-mobility graphene hetero-stacks relying on chemical vapour deposited graphene [5] and used them to fabricate photobolometers integrated on passive  $Si_3N_4$  waveguides [6]. By exploiting their bias-dependent photoresponsivity, these photobolometers can mix an electrical baseband signal with an optical one and upconvert it.

We report graphene-based photobolometers performing >4Gb/s datarate transmission and working at frequencies >96 GHz, with potential applications up to the D-band (130-170 GHz).

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